

06-23-2005

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## 1. Name of conveying party(ies):

Chao-Cheng Lee  
Tzung-Ming Chen  
Chieh-Min Feng

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

## 2. Name and address of receiving party(ies):

Name: Realtek Semiconductor Corp.Address: No. 2, Industry E. Road IXScience-Based Industrial ParkCity: Hsinchu State/Prov.: \_\_\_\_\_Country: Taiwan, R.O.C. ZIP: \_\_\_\_\_

Additional name(s) &amp; address(es)

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## 3. Nature of conveyance:

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Execution Date: February 17, 2005

## 4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: 2/17/05

Patent Application No.

Filing date

B. Patent No.(s)

06/22/2005 DBYRNE 00000196 11154759

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Additional numbers

☐ Yes ☐ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Raymond SunRegistration No. 35,699Address: 12420 Woodhall WayCity: Tustin State/Prov.: CACountry: U.S.A. ZIP: 92782

## 6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☐ Authorized to be charged to deposit account

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## 9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*Raymond Sun

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2-17-05

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**ASSIGNMENT**

INVENTOR(S): LEE, Chao-Cheng  
CHEN, Tzung-Ming  
FENG, Chieh-Min

In consideration of the sum of one U.S. dollar (US\$1.00) and other good and valuable consideration paid to each of the undersigned, the undersigned agree to assign, and hereby does assign, transfer and set over to Realtek Semiconductor Corp., of Taiwan, R.O.C., having an address of No. 2, Industry E. Road IX, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C. (hereinafter designated the "Assignee") the entire worldwide right, title and interest in the invention known as Amplifying Circuit with Variable Supply Voltage which the undersigned have executed an application for patent in the United States of America on 2-17-05.

The undersigned agree to execute all papers necessary in connection with the application and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the international Convention for Protection of Industrial Property or similar agreements.

The undersigned agree to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize and request the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or continuing applications thereof to Assignee, as Assignee of the entire interest, and hereby covenant that they have full right to convey the entire interest herein assigned, and that they have not executed and will not execute any agreement in conflict herewith.

The undersigned hereby grant RAYMOND SUN, Reg. No. 35,699, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent & Trademark Office for recordation of this document.

Dated: 2005.2.17.

Signature: Chao-Cheng Lee  
LEE, Chao-Cheng

Dated: 2005.02.17

Signature: T.M. Chen  
CHEN, Tzung-Ming

Dated: Feb. 17 2005

Signature: Feng Chieh-Min  
FENG, Chieh-Min